## LNJ937W8CRA

### Hight Bright Surface Mounting Chip LED

#### ESS II Type

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	P <sub>D</sub>	40	mW	
Forward current	$I_{\mathrm{F}}$	10	mA	
Pulse forward current *	I <sub>FP</sub>	55	mA	
Reverse voltage	V <sub>R</sub>	5	V	
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

Note) \*: The condition of I<sub>FP</sub> is duty 10%, Pulse width 1 msec.

#### ■ Lighting Color

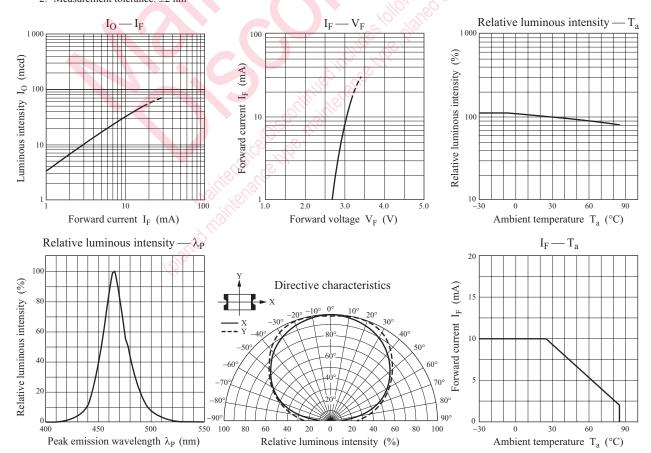
• Blue

#### ■ Electro-Optical Characteristics $T_a = 25$ °C±3°C

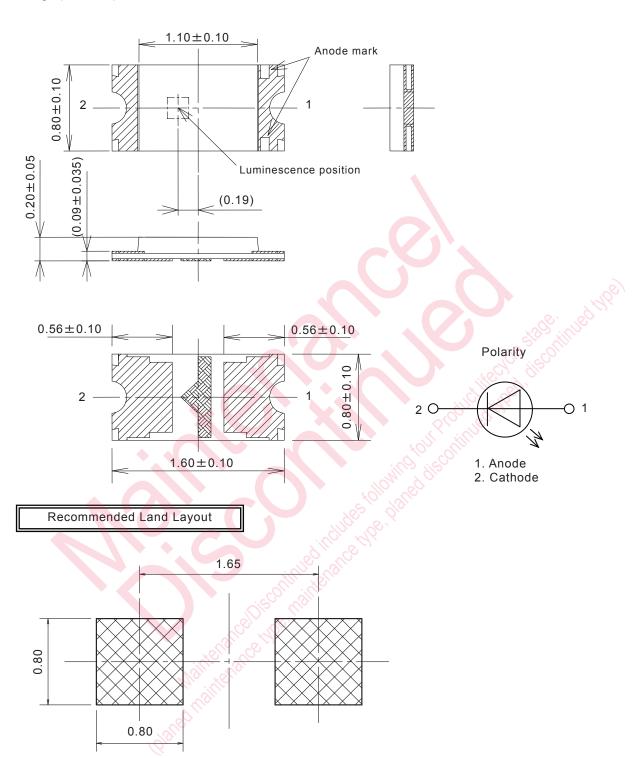
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *1	I <sub>O</sub>	$I_F = 5 \text{ mA}$	10.0	17.0	30.0	mcd
Reverse current	$I_R$	$V_R = 5 V$		W/O/O Xi	100	μΑ
Forward voltage	V <sub>F</sub>	$I_F = 5 \text{ mA}$		2.9	3.2	V
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 5 \text{ mA}$	"ANC"	465		nm
Dominant emission wavelength *2	$\lambda_{ m d}$	$I_F = 5 \text{ mA}$	462	472	478	nm
Spectral half band width	Δλ	$I_F = 5 \text{ mA}$	dille	20		nm

Note) \*1: Measurement tolerance: ±20%

<sup>\*2:</sup> Measurement tolerance: ±2 nm



#### ■ Package (Unit: mm)



(Note1)Electrode projection is not included in the package dimensions.
(Note2)About solder thickness, please examine the products yourself completely.

(Recommended thickness: t=0.10 mm∼0.15 mm)

2 Ver. BEK

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